



# Product data sheet

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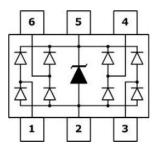
## TPD4E001DBVR-MS

Semiconductor Compiance



SOT-23-6

#### Pin Config uration



#### Features

- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
    Air discharge: ±15kV
    Contact discharge: ±10kV
  - IEC61000-4-4 (EFT) 40A (5/50ns)
  - IEC61000-4-5 (Lightning) 5A (8/20 μs)
- RoHS Compliant

#### **Applications**

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports

## **Mechanical Characteristics**

- Package: SOT-23-6
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel:3,000pcs
- Reel Size:7inch

#### Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20µs)	Ррр	80	W
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	±15	Kv
ESD per IEC 61000-4-2 (Contact)	VESD	±10	rv
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T <sub>STJ</sub>	-55 to +150	°C





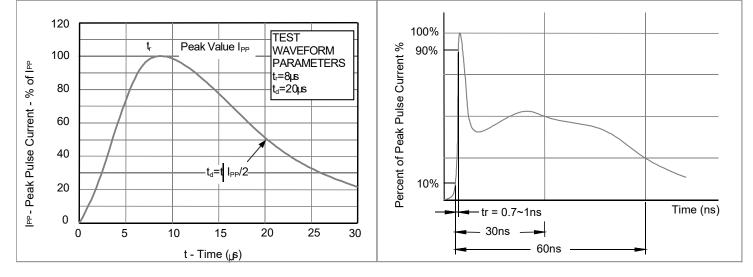
#### Electrical Characteristics (TA=25°C unless otherwise specified)

P/N	V <sub>RWM</sub> (V)	V <sub>br</sub> (V)	l⊤ (mA)	Vc @1A	(Max)	/c (@A)	l <sub>ℝ</sub> μΑ (Max)	C (Pf) (Typ.)
TPD4E001DBVR-MS	5	6	1	12	16	5	1	0.6

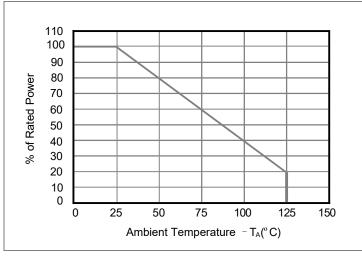
## **Characteristic Curves**

#### Fig1. 8/20<sup>µ</sup> sPulse Waveform

#### Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)



#### Fig3. Power Derating Curve



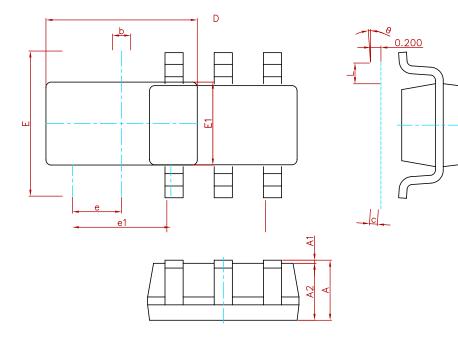


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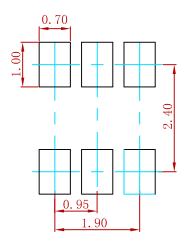
Roms

## PACKAGE MECHANICAL DATA



Symbol	Dimensions In	n Millimeters	Dimensions In Inches		
Synbol	Min.	Max.	Min.	Max.	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
E	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

### Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters. 2.General tolerance:± 0.05mm.

3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
TPD4E001DBVR-MS	SOT-23-6	3000



TPD4E001DBVR-MS

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